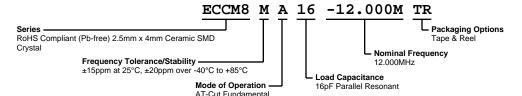
ECCM8MA16-12.000M TR





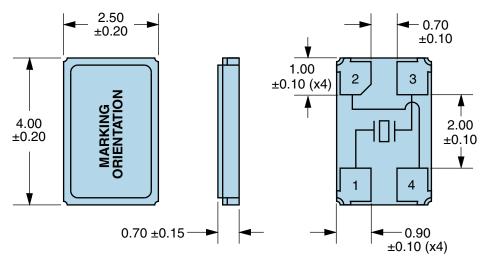




| ELECTRICAL SPECIFICATIONS | | |
|-------------------------------------|--|--|
| Nominal Frequency | 12.000MHz | |
| Frequency Tolerance/Stability | ±15ppm at 25°C, ±20ppm over -40°C to +85°C | |
| Aging at 25°C | ±3ppm/Year Maximum | |
| Load Capacitance | 16pF Parallel Resonant | |
| Shunt Capacitance (C0) | 5pF Maximum | |
| Equivalent Series Resistance | 100 Ohms Maximum | |
| Mode of Operation | AT-Cut Fundamental | |
| Drive Level | 100μWatts Maximum, 10μWatts Correlation | |
| Crystal Cut | AT-Cut | |
| Spurious Response | >3dB from Fo to Fo+5000ppm | |
| Drive Level Dependancy (DLD2) | 20% of Maximum ESR Limit (from 1μWatt to 100μWatt) | |
| Insulation Resistance | 500 Megaohms Minimum at 100Vdc | |

| ENVIRONMENTAL & MECHANICAL SPECIFICATIONS | | |
|---|---|--|
| ESD Susceptibility | MIL-STD-883, Method 3015, Class 1, HBM: 1500V | |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A | |
| Flammability | UL94-V0 | |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C | |
| Mechanical Shock | MIL-STD-883, Method 2002, Condition B | |
| Moisture Resistance | MIL-STD-883, Method 1004 | |
| Moisture Sensitivity | J-STD-020, MSL 1 | |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K | |
| Resistance to Solvents | MIL-STD-202, Method 215 | |
| Solderability | MIL-STD-883, Method 2003 | |
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B | |
| Vibration | MIL-STD-883, Method 2007, Condition A | |

MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION |
|-----|--------------|
| 1 | Crystal |
| 2 | Cover/Ground |
| 3 | Crystal |
| 4 | Cover/Ground |

| LINE | MARKING |
|------|---|
| | E12.0 E=Ecliptek |
| 2 | XXXXX XXXXX=Ecliptek Manufacturing Identifier |